

## PW03N10KE

### 100V N-Channel MOSFET

3A 100V;  $R_{DS(ON)typ}=69m\Omega@10V$ ,  $R_{DS(ON)typ}=84m\Omega@4.5V$

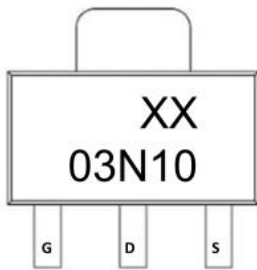
#### FEATURE

- Trench Technology Power MOSFET
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance

#### Application

- Power Switching Application

#### MARKING:

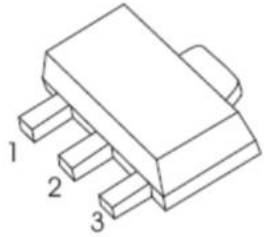


03N10 = Device Code

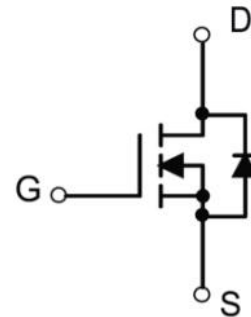
XX = Date Code

#### SOT-89

1. GATE
2. DRAI
3. SOURCE



#### Schematic diagram



#### ABSOLUTE MAXIMUM RATINGS ( $T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>(1)</sup>	$I_D$	6	A
Continuous Drain Current <sup>(5)</sup>	$I_D$	3	A
Pulsed Drain Current <sup>(2)</sup>	$I_{DM}$	12	A
Power Dissipation <sup>(4)</sup>	$P_D$	2.7	W
Power Dissipation <sup>(5)</sup>	$P_D$	1.5	W
Thermal Resistance from Junction to Ambient <sup>(5)</sup>	$R_{\theta JA}$	80	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	45	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~ +150	$^\circ\text{C}$

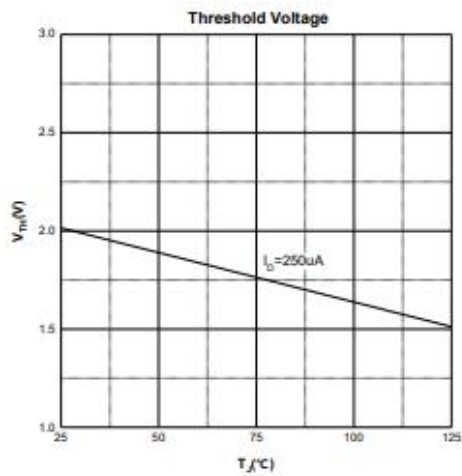
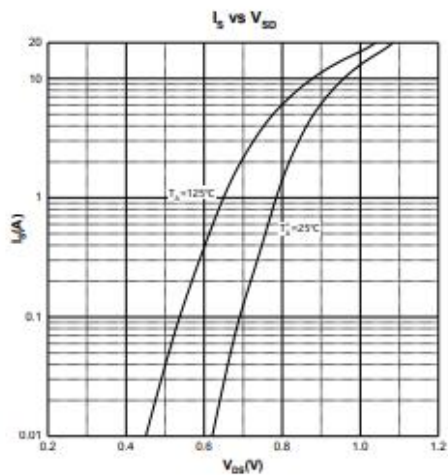
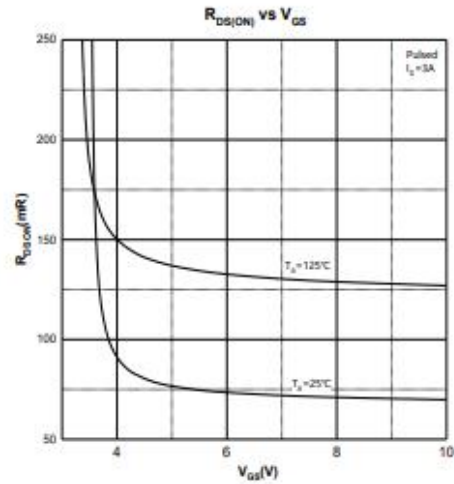
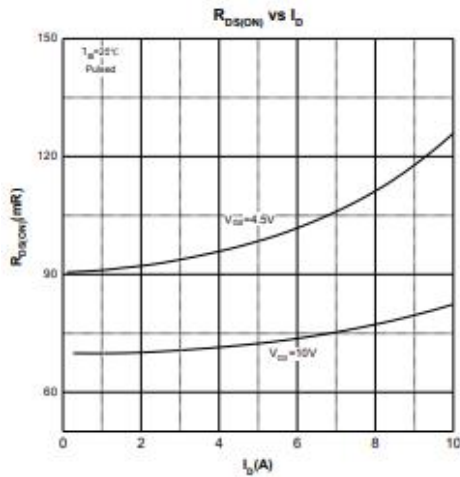
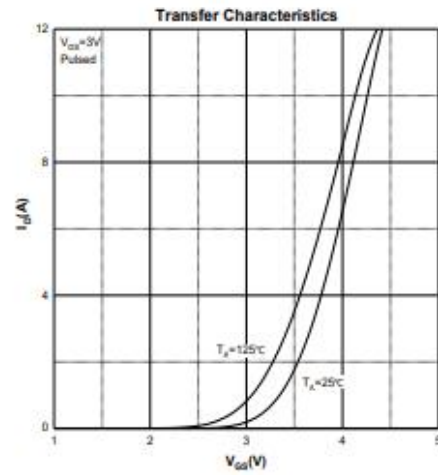
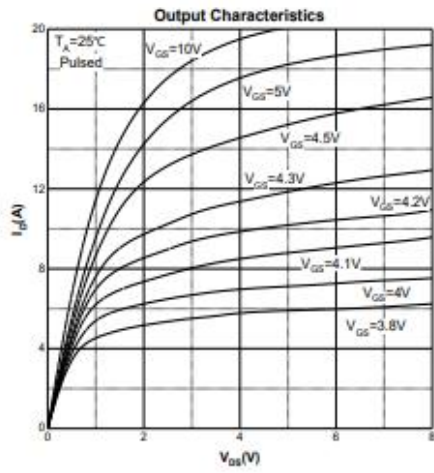
**MOSFET ELECTRICAL CHARACTERISTICS(T<sub>a</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	100			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 80V, V <sub>GS</sub> = 0V			1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
<b>ON CHARACTERISTICS<sup>(3)</sup></b>						
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1	2	3	V
Drain-source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 3A		68	140	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3A		84	150	
Forward tranconductance	g <sub>FS</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 3A	3			S
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0V, f = 1MHz		790		pF
Output Capacitance	C <sub>oss</sub>			31		
Reverse Transfer Capacitance	C <sub>rss</sub>			28		
Gate Resistance	R <sub>g</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz		1.3		Ω
<b>SWITCHING CHARACTERISTICS</b>						
Turn-on delay time	t <sub>d(on)</sub>	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 50V, R <sub>L</sub> = 17Ω, R <sub>G</sub> = 1Ω		17		ns
Turn-on rise time	t <sub>r</sub>			7		
Turn-off delay time	t <sub>d(off)</sub>			35		
Turn-off fall time	t <sub>f</sub>			6		
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 50V, I <sub>D</sub> = 3A, V <sub>GS</sub> = 10V		18		nC
Gate-Source Charge	Q <sub>gs</sub>			3		
Gate-Drain Charge	Q <sub>gd</sub>			3.6		
<b>SOURCE-DRAIN DIODE CHARACTERISTICS</b>						
Diode Forward voltage <sup>(3)</sup>	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 3A			1.2	V

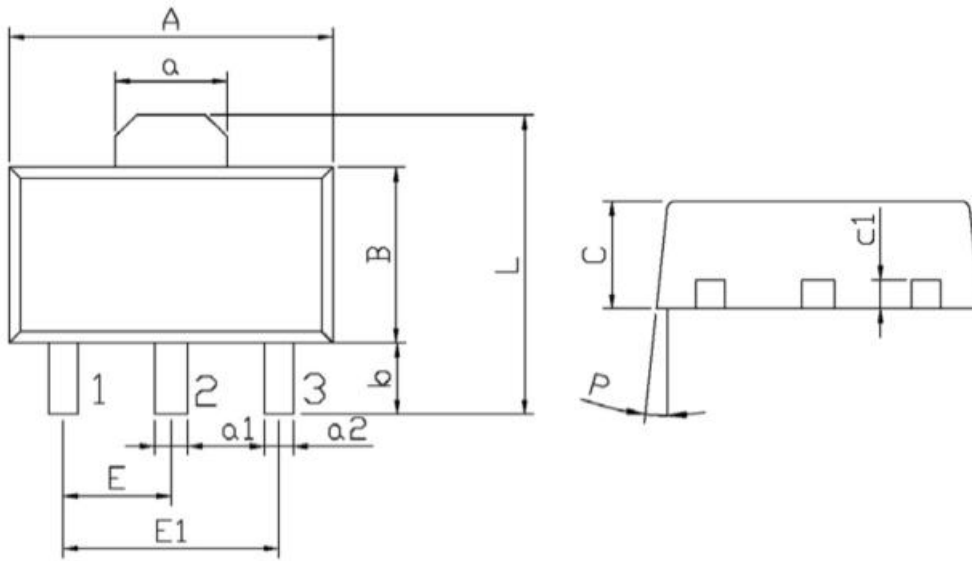
**Notes:**

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width ≤ 10μs, duty cycle ≤ 1%.
- 3.Pulse Test : Pulse Width ≤ 300μs, duty cycle ≤ 2%.
- 4.The power dissipation PD is limited by T<sub>J(MAX)</sub> = 150°C.And device mounted on a large heatsink
- 5.Device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub> = 25°C.

**Typical Electrical and Thermal Characteristics**



**SOT-89 Package Information**



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	4.4	4.7	a1	0.36	0.56
B	2.35	2.65	a2	0.30	0.50
L	3.878	4.478	C	1.40	1.70
a	1.45	1.65	c1	0.35	0.50
E	1.40	1.60	P	6°	
E1	2.80	3.20			
b	0.80	1.20			

单位：mm